

REMARKS

Reconsideration of this application, as amended, is respectfully requested.

In the Office Action, the Examiner listed several claim objections based on grammatical errors in the claims. In addition, the Examiner rejected the claims under 35 U.S.C. § 112, second paragraph based on several instances of a lack of antecedent basis and other wording in the claims that allegedly made the claims vague and difficult to understand. In response to the objections and § 112, second paragraph rejections, claims 1 through 11 have been amended to more clearly recite the various features of the semiconductor device so that the claims now particularly point out and distinctly claim the subject matter which the applicant regards as his invention.

As recited in claim 1, the semiconductor device comprises a semiconductor member having a plurality of electrode terminals. The device also includes a mounting member having a plurality of interconnect pads, electrically and mechanically connected to the respective electrode terminals for mounting the semiconductor member on the mounting member. The interconnect pads form a plurality of I/O cells that include signal terminals. The I/O cells are comprised of first and second groups in which the second group is disposed in an inner position of the mounting member with respect to the first group.

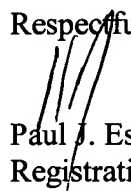
In the Office Action, the Examiner rejected claims 1 and 2 under 35 U.S.C. § 102 (e) as being anticipated by Terui. The Examiner contends that Terui teaches all the features of claim 1, relying on Figs. 1 and 2A. Figure 1 is a cross-sectional view of a semiconductor device and, therefore, cannot disclose first and second groups of I/O cells in which the second group is disposed on an inner position with respect to the first group. Figure 2A is a plan view of a

semiconductor device showing a single group of electrode pads surrounding the periphery of the device. There is no disclosure in Figure 2A or in any of the other figures or in the disclosure of the Terui patent of first and second groups of I/O cells in which the second group is disposed in an inner position on the mounting member with respect to the first group. As shown in Figures 2B and 6A, the Terui device has a single group of electrode pads 2 and there is no disclosure of a second group of pads disposed in an inner position with respect to the first group.

It is noted that the Examiner only identified a rejection under 35 U.S.C. § 102 (e) of claims 1 and 2, although within Section 11 of the Office Action, claim 6 appears to be also rejected based on Terui. However, no rejections were identified with respect to the remaining claims.

In view of the above, it is respectfully submitted that all of the claims pending in the application contain patentable subject matter and the Notice of Allowance is respectfully solicited.

Respectfully submitted,


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